Abstract

Method of recovering a bonding apparatus from a bonding failure

A method of recovering a bonding apparatus from a bonding failure to resume a normal operating state for semiconductor chip fabrication is disclosed. The bonding apparatus comprises: i) a bonding tool for bonding a wire between a semiconductor chip and a substrate; and ii) a position sensor. Specifically, the method comprises the steps of: a) the position sensor determining a position of the bonding tool when the bonding tool contacts a surface to bond the wire to the substrate; b) the bonding apparatus detecting a bonding failure caused by detachment of the semiconductor from the substrate based on the position of the bonding tool; and c) the bonding apparatus detaching the semiconductor chip from the wire.

[FIG. 3]